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CLMPTO 07/19/04 CM.

CLAIMS 1-13. (CANCELLED)

CLAIMS 14-19. (WITHDRAWN)

20. (Amended) An integrated circuit, comprising:

a logic inverter comprising:

an n-channel field effect transistor;

a p-channel field effect transistor;

a gate, formed in a layer of polysilicon; and

a connection between a drain of the p-channel field effect transistor and a drain of the n-channel field effect transistor formed in said same layer of polysilicon.

- 21. (Amended) The integrated circuit as described in claim 20, wherein the polysilicon comprising said gate is coplanar with the polysilicon comprising said connection between said drain of the p-channel field effect transistor and said drain of the n-channel field effect transistor.
- 22. (Previously Presented) The integrated circuit as described in claim 20, further comprising:
 - a first layer of metallization; and
- a second layer of metallization, wherein the second layer of metallization comprises substantially no local interconnect.

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- 23. (Previously Presented) The integrated circuit as described in claim 22, wherein said second layer of metallization comprises no local interconnect.
- 24. (Amended) The integrated circuit as described in claim 20, further comprising:
 - a plurality of MACROs;
 - a fist first layer of metallization; and
 - a second layer of metallization interconnecting said plurality of MACROs.

CLAIM 25. (CANCELLED)

- 26. (Previously Presented) The integrated circuit as described in claim 24, further comprising, no local interconnect within said second layer of metallization in at least one of said MACROs.
- 27. (Previously Presented) The integrated circuit as described in claim 24, further comprising, no local interconnect within said second layer of metallization in a plurality of said MACROs.

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28. (Previously Presented) The integrated circuit as described in claim 24, further comprising, no local interconnect within said second layer of metallization in all of said plurality of MACROs.

- 29. (Previously Presented) The integrated circuit as described in claim 24, wherein at least one of said MACROs is comprised by a standard cell array of the integrated circuit.
- 30. (Previously Presented) The integrated circuit as described in claim 29, wherein said standard cell array comprises a row pitch and at least one MACRO has a row pitch equivalent to the row pitch of said standard cell array.